

Abstract of the Disclosure

A method and a machine for assembling a blister sheet and a linerboard, the board optionally having a flap. The blister sheet, the linerboard and the optional flap are flat stacked on top of one another; and the layers are subsequently heat sealed, preferably by means of thermal conduction or induction between a counter electrode and an electrode, continuously and in respective closed circuits, in order to produce cases for packaging such items as medicaments, electronic components, small tools, perfume samples or any other product which is to be enclosed in at least one bubble of the blister sheet.